

TECHNICAL CHARACTERISTICS

1. General Characteristics

Dimension: 12.30L x 10.05W x 1.35H mm
Weight: Approx. 0.6 g
Contact principle: Friction technology
Operating position: Shaft up / Down / Horizontal
Mounting System: SMT Type (with post)
Durability: 3,000 cycles min.

2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0
RoHS Directive 2011/65/EU Compliant

3. Electrical Characteristics

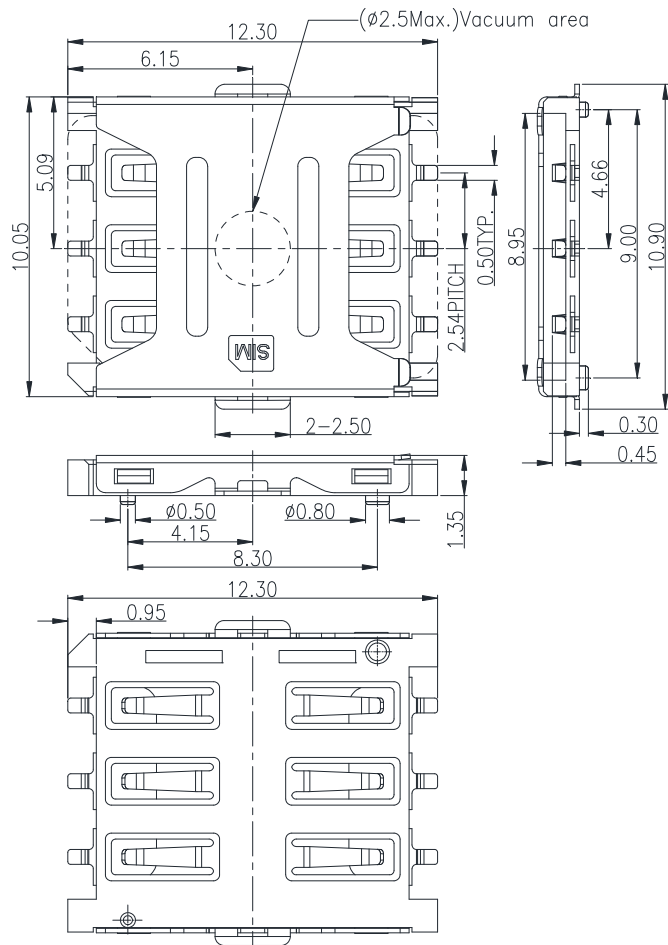
Number of contacts: 6 pins
Contact resistance: 100 mΩ max.
Insulation resistance: >1000 MΩ / 500 VDC

4. Solderability

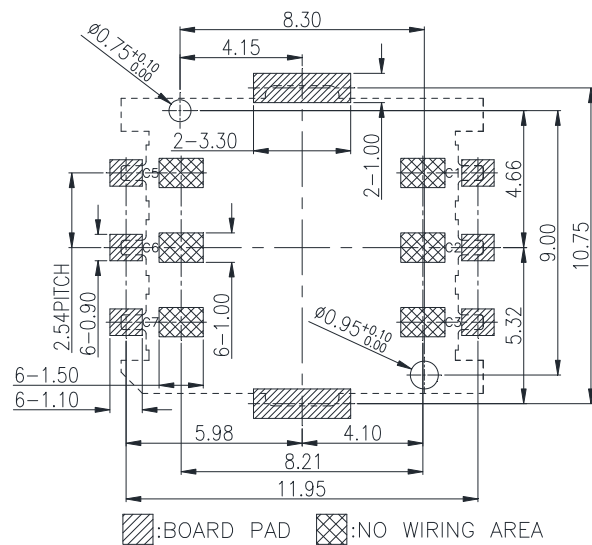
Wave: Not applicable
IR reflow: 260°C, 10 sec. Max.
Manual soldering: 360°C, 3 sec. Max.

5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C
Operating humidity: 10 % ~ 95 % RH
Storage temperature: - 40°C ~ + 85°C
Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm
Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm
Reference dimension for PCB layout

HB Nano SIM Card Connector

Model No.: ICC-N06

Revision: 0.9

Date: JUL. 15, 2019

Note:

1. Coplanarity of solder pins 0.10mm max.
2. Recommended thickness of solder paste > 0.15mm.